



## Material Content Data Sheet



<b>Sales Product Name</b>		ESD206-B1-02ELS E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001119580						
<b>Package</b>		PG-TSSLP-2-3		<b>Weight*</b>		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.17		1669	
	noble metal	gold	7440-57-5	0.001	0.65		6467	
	inorganic material	silicon	7440-21-3	0.010	4.79	5.61	47930	56066
leadframe	non noble metal	nickel	7440-02-0	0.108	51.69	51.69	516990	516990
wire	non noble metal	copper	7440-50-8	0.001	0.72	0.72	7170	7170
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1880	
	plastics	epoxy resin	-	0.011	5.46		54569	
	inorganic material	silicondioxide	60676-86-0	0.067	31.99	37.64	319896	376345
leadfinish	noble metal	gold	7440-57-5	0.004	1.76	1.76	17640	17640
plating	noble metal	palladium	7440-05-3	0.001	0.61		6117	
	noble metal	gold	7440-57-5	0.004	1.97	2.58	19672	25789
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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